

Origin

Vacuum Reflow-Soldering System

for power devices

Origin Flux-less Soldering

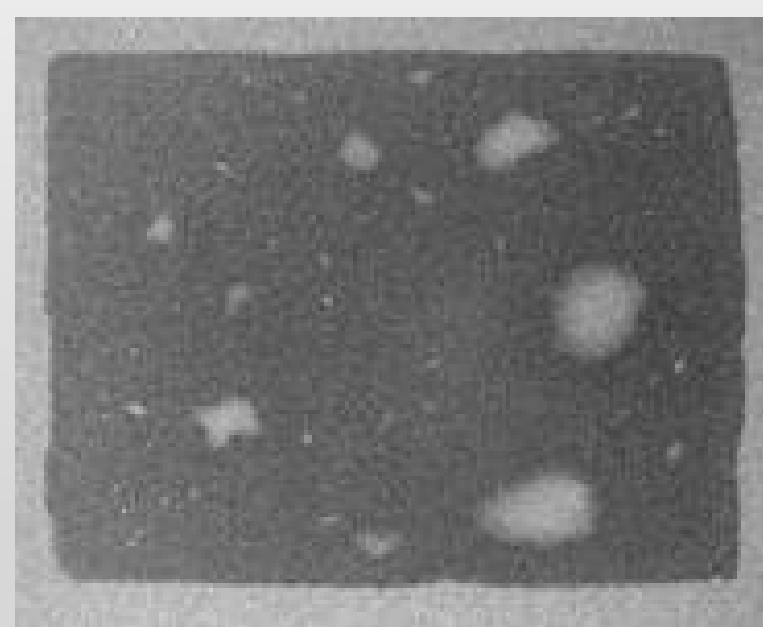
- Requires no flux and its cleaning
- Creates no splash in process and results no void
by utilizing **formic acid reduction** and **compression process**

Soldering result

Pb-free solder (Sn/Ag/Cu)

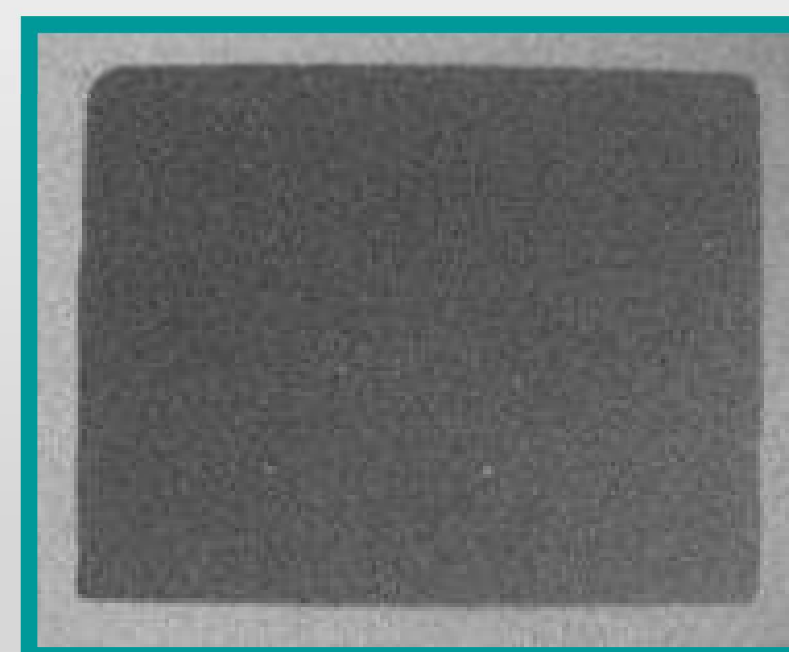
Hydrogen
reduction
and
non vacuum
process

Conventional
process



VS

Origin
Flux-less Soldering



**Formic acid
reduction
and
compression
process**

- X-ray photo -

Advantages

- **Safe operation of formic acid** by closed system
- **Short cycle time** by high speed temperature control under vacuum condition
- **Small footprint and easy expansion** by simple modular design

Specifications

Model	VS2
Solder type	<i>Flux-less solder</i>
Reducing agent	Formic acid
Heating	IR heaters Max.450°C
Cooling	Water-cooled plate
Cycle time	Standard 7.5min
Process area	W200 x D250 x H60mm
Dimensions	W850 x D850 x H1,460mm



Origin ELECTRIC CO., LTD.